

PRODUCT/PROCESS CHANGE NOTIFICATION

TO: ME-UK: AR
ME-Italy: BE
ME-France: BA
ME-CE: MEA

DATE: 16. April 2014
FROM: MEU Mktg / Eng
Dr. P. Stelmaszyk

DEPT.: SEMI

CC: MK, KO, PM, RJ, BK, BU, JN, ST, TGH, SR,
DC, IL, JL, HE, SB, MG

PCN number : PCN-H-05-14

Herewith we want to inform you about the following:

- a) Product change:
Process change:
- b) Old Mitsubishi type number: **Change of heat sink material for SiRF modules:
here H46S modules.**
- c) New Mitsubishi type number: **No change**
- d) Expected last order and shipment dates
for unchanged devices to be supplied: **Not applicable**
- e) Expected first shipment date of
changed devices: **June 2014 (ex-works)**
- f) Manufacturing location and product line
affected:
- g) Description of the proposed change: **Change from EFETC copper to Tough-Pitch
copper.**
- h) Comparison table of change attached: Yes No
- i) Reliability and/or engineering test data
are: attached:
available on request:
- j) Customer spec. / part number: all included


(Signature of Mgr HF/OPTO Marketing/ Engineering)

Note: Please comment until 14th May 2014. Otherwise we regard the PCN as accepted.